

Manufacturing Bulletin

Subject: Shipping Container Change – Tray Shipment

(Revised to add BGA and FCBGA and to clarify the affected package

list*)

Date: September 12, 2006

Integrated Device Technology, Inc. will introduce a smaller shipping box for products shipped in trays as listed in the attachment. The purpose of this change is to improve the storage space. There is no change in the standard or custom shipping labels, number of tray per stack and quantity per tray. The end caps are retained and will now have a cushion ring for added protection. This new shipping box has been tested and meets ASTM D5276-98, Standard Test Method for Drop Test of Loaded Containers by Free Fall.

During the transition period, customers may receive shipments in either box type.

Yours sincerely,

PS Tow

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ATTACHMENT

Subject: Shipping Container Change – Tray Shipment

Date: September 12, 2006

AFFECTED PACKAGE LIST:

BGA*, FCBGA*, TQFP, PQFP (except 28mm x 28mm*), VQFP-N and TSOP

EXISTING BOX

Dimension Details

402 x 202 x 96 mm 4+1 per bundle PP-strap (4+1) End-cap Desiccant (2 units) & HIC *

Moisture Barrier Bag *
Paper cap

* These are required only for moisture sensitive (MSL 3) products.

Photos

Existing Box



New Box

NEW BOX

368 x 169 x 56 mm

Desiccant (2 units) & HIC *

Moisture Barrier Bag *

4+1 per bundle

PP-strap (4+1)

Cushion ring

End-cap



The above example is the dry pack method for MSL 3 products. Non-moisture sensitive (MSL1) products do not require dry packing.



